

DESCRIPTION

The AM5352 is the N-Channel logic enhancement mode power field effect transistor which is produced using high cell density advanced trench technology to provide excellent R_{DS(ON)}.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, and low in-lin power loss are needed in a very small outline surface mount package

The AM5352 is available in SC89-3 (SOT-523) package.

ORDERING INFORMATION

Package Type	Part Number			
SC89-3	CK3	AM5352CK3R		
(SOT-523)	CNS	AM5352CK3VR		
Note	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				
Suffix " V " means Halogen free Package				

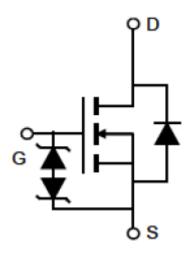
FEATURES

- = 20V/0.6A, R_{DS(ON)}=200mΩ(typ.)@V_{GS}=4.5V
- 20V/0.5A, $R_{DS(ON)}=240m\Omega(typ.)@V_{GS}=2.5V$
- 20V/0.4A, $R_{DS(ON)}$ =420m Ω (typ.)@V_{GS}=1.8V
- Super high design for extremely low R_{DS(ON)}
- Exceptional on-resistance and Maximum DC current capability
- ESD Protected
- Available in SC89-3 (SOT-523) Package

APPLICATION

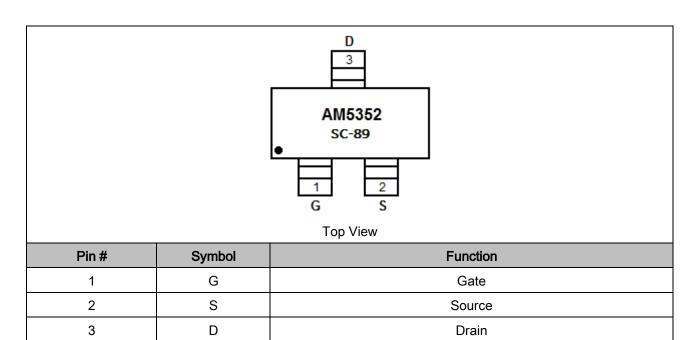
- Power Management in Note Book
- Portable Equipment
- Battery Powered System

TYPICAL APPLICATION



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PIN DESCRIPTION



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ABSOLUTE MAXIMUM RATINGS

T_A= 25°C, Unless otherwise noted

V _{DSS} , Drain-Source Voltage	20V		
V _{GSS} , Gate-Source Voltage		±12V	
I _D , Continuous Drain Current	T _A =25°C,V _{GS} =10V	0.7A	
	T _A =75°C,V _{GS} =10V	0.56A	
I _{DM} , Pulsed Drain Current	1A		
Is, Continuous Source Current (Diode Conduction)		0.15A	
D. Davisa Diagination	T _A =25°C	0.27W	
P _D , Power Dissipation	T _A =75°C	0.16W	
T _J , Operation Junction Temperature		150°C	
T _{STG} , Storage Temperature Range		-55°C~+150°C	
R _{θJA} , Thermal Resistance-Junction to Ambient		62.5°C/W	

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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ELECTRICAL CHARACTERISTICS

T_A=25°C, Unless otherwise noted

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.3		0.8	V
Gate Leakage Current	Igss	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0 V _{DS} =20V, V _{GS} =0 T _J =55°C			1 5	uA
Curroni		V _{GS} =4.5V, I _D =0.6A		300	360	
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =0.5A		240	420	$m\Omega$
		V _{GS} =1.8V, I _D =0.4A		420	560	
Forward Transconductance	Gfs	V _{DS} =10V, I _D =0.4A				S
Source-Drain Diode						
Diode Forward Voltage	V_{SD}	I _S =0.15A, V _{GS} =0V		0.65	1.2	V
Dynamic Parameters						
Total Gate Charge	Q_g	V _{DS} =10V		1.06	1.38	
Gate-Source Charge	Q_gs	V _{GS} =4.5V		0.18		nC
Gate-Drain Charge	Q_{gd}	I _D =0.6A		0.32		
Input Capacitance	Ciss	V _{DS} =10V		70		
Output Capacitance	Coss	V _{GS} =0V		20		pF
Reverse Transfer Capacitance	Crss	f=1MHz		8		
Turn-On Time	T _{d(on)}	V _{DS} =10V		18	26	
	Tr	I _D =0.5A		20	28	
Turn-Off Time	$T_{d(off)}$	V _{GEN} =4.5V		70	110	nS
	T _f	$R_G=1\Omega$		25	40	

NOTE1: Pulse test: pulse width<=300uS, duty cycle<=2%

NOTE1: Static parameters are based on package level with recommended wire bonding

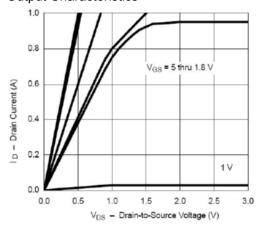
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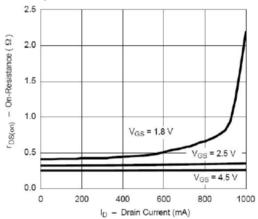
TYPICAL PERFORMANCE CHARACTERISTICS

25°C, Unless Note

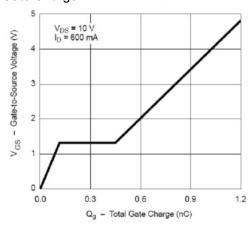
1. Output Characteristics



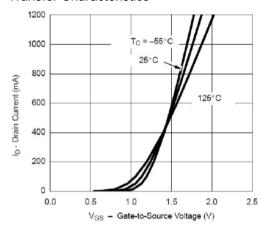
3. On-Regions vs. Drain Current



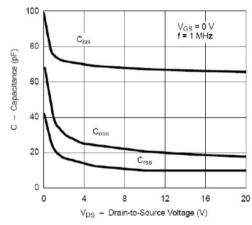
5. Gate Charge



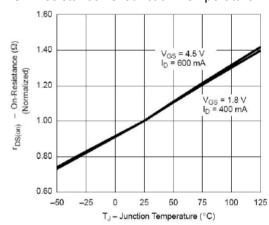
2. Transfer Characteristics



4. Capacitance



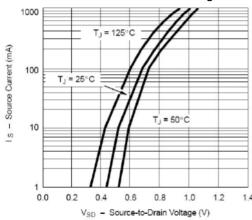
6. On-Resistance vs. Junction Temperature



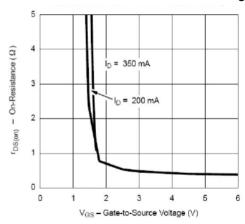
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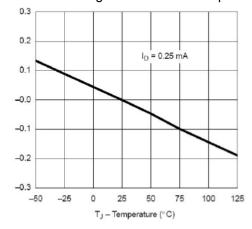
7. Source-Drain Diode Forward Voltage



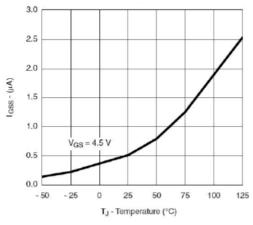
8. On-Resistance vs. Gate-to-Source Voltage



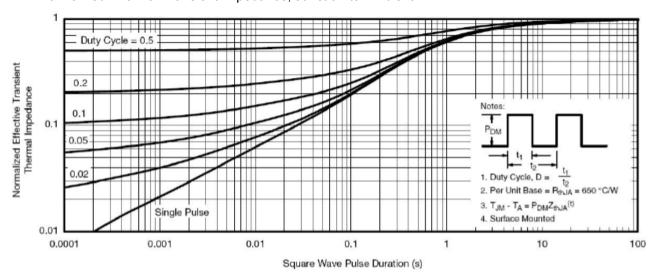
9. Threshold Voltage Variance vs. Temperature



10. IGGS vs. Temperature



11. Normalized Thermal Transient Impedance, Junction-to-Ambient

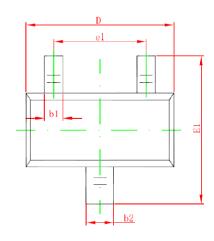


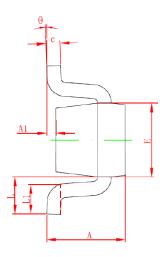
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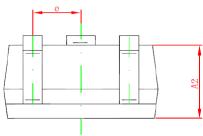


PACKAGE INFORMATION

Dimension in SC89-3 (SOT-523) Package (Unit: mm)







SYMBOL	MIN	MAX		
Α	0.700	0.900		
A1	0.000	0.100		
A2	0.700	0.800		
b1	0.150	0.250		
b2	0.250	0.350		
С	0.100	0.200		
D	1.500	1.700		
Е	0.700	0.900		
E1	1.450	1.750		
е	0.500(TYP)			
e1	0.900	1.100		
L	0.400(REF)			
L1	0.260	0.460		
θ	0° 8°			

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